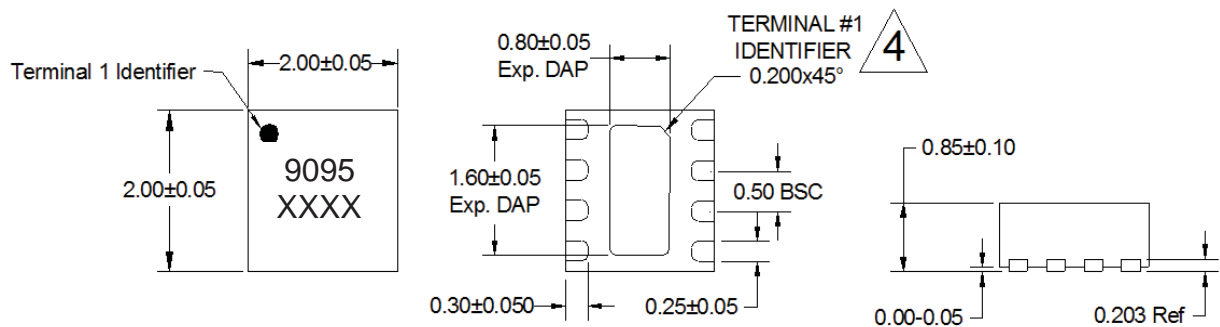


## Mechanical Information

### Package Marking and Dimensions

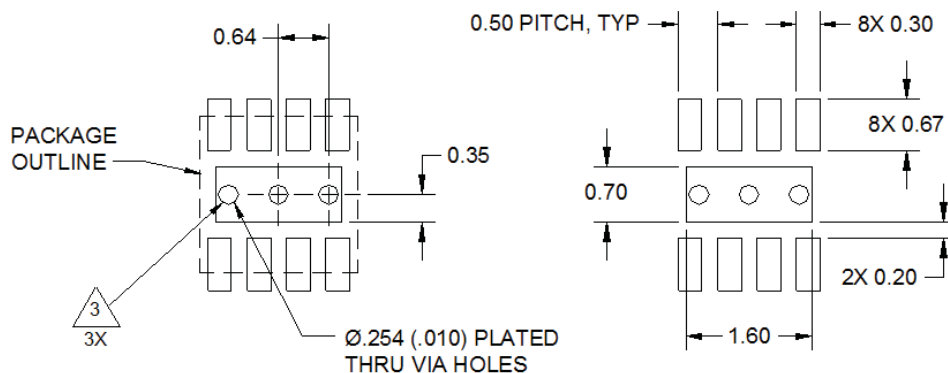
Marking: Part number – 9095  
Lot code – XXXX



#### Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Except where noted, this part outline conforms to JEDEC standard MO-220, Issue E (Variation VGGC) for thermally enhanced plastic very thin fine pitch quad flat no lead package (QFN).
3. Dimension and tolerance formats conform to ASME Y14.4M-1994.
4. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.

### PCB Mounting Pattern



#### Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a  $0.35$  mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of  $0.25$  mm ( $0.10$ ").
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.